

C1
in Figs. 4A and 4B, by using the bonding tool 8 and a stage 9 of which the parallelism is controlled so as to be adjusted to, for example, about 5 μm or less, heat and load are locally applied to the circuit board 4 through the IC chip 1 from the side of the bonding tool 8 toward the side of the stage 9, so that the warp of the portion of the circuit board 4 receiving the heat and load is corrected. The IC chip 1 is warped with a concave portion located around the center of its active surface. By pressurizing this with a heavy load of not smaller than 20 gf in the bonding stage, the warp and undulation of both the board 4 and the IC chip 1 can be corrected. The warp of the IC chip 1 is generated by an internal stress occurring when the IC chip 1 is formed, that is, when a thin film is formed on Si.

Please replace the paragraph beginning at page 33, line 18, to page 34, line 4, with the following rewritten paragraph:

C2
In this case, the circuit board 4 is provided by a multilayer ceramic board, a glass cloth base epoxy copper clad laminate board (glass epoxy board), an aramid unwoven fabric board, a glass cloth base polyimide resin copper clad laminate board, FPC (Flexible printed circuit board), or the like. These boards 4 have warp and undulation due to thermal hysteresis, cutting, and processing, meaning that their surfaces are not the completely flat surfaces. Therefore, by locally applying heat and load to the circuit board 4 through the IC chip 1, the warp of the portion that belongs to the circuit board 4 and has received the heat and load is corrected.

IN THE CLAIMS

Please amend the claims as follows:

Sub 3
50. (Amended) A method as claimed in claim 39, wherein, prior to said aligning, said thermosetting resin, in the form of a solid thermosetting resin sheet having on at least one surface thereof a flux layer, is applied to said circuit board, and said bonding is executed by said hardening said sheet while simultaneously performing said correcting by pressing said electronic component toward said circuit board by a heated head, thereby causing said bumps to break

Cont
C3
Sub 37
through said sheet and causing said bumps to bond to said electrodes of said circuit board due to adhesion of a flux component of said flux layer to said bumps.

52. (Amended) A method of mounting an electronic component, said method comprising:

aligning in position electrodes of said electronic component with electrodes of a circuit board, with interposition between said electronic component and said circuit board of insulative thermosetting resin;

CH
hardening with heat said thermosetting resin interposed between said electronic component and said circuit board, while achieving mutual pressing between said electronic component and said circuit board, thereby correcting any warping of said circuit board, and thereby bonding said electronic component and said circuit board together to achieve electrical connection between said mutual electrodes thereof;

wherein, prior to said aligning, said thermosetting resin, in the form of a solid thermosetting resin sheet having holes formed at positions corresponding either to said bumps or to said electrodes of said circuit board and extending in a direction of extension of said bumps, with particles being embedded and electrically continuous in said holes, said particles comprising resin balls having surfaces plated with gold, nickel particles, conductive particles made of silver, silver-palladium or gold, conductive paste, or gold balls, is applied to said electrodes of said circuit board by positional alignment, and said bonding is executed by said hardening said sheet by application of heat thereto while conducting said pressing by forcing said electronic component toward said circuit board; and

wherein each of said particles has a size greater than a thickness of a passivation film to be coated on at least said electrodes of said electronic component and smaller than a thickness of one of said electrodes of said circuit board, and said bonding further is executed by applying ultrasonic vibrations to said electronic component.